

Cancel claims 11, 34 and 36-53.

D2


1 20. (thrice amended) A package for containing electronic components, the
2 package comprising:
3 a first circuitized card having a top and bottom surface;
4 a second circuitized card having a top and bottom surface;
5 an interposer having an opening, a top surface, and a bottom surface, the
6 interposer being electrically connected to the first circuitized card and the second
7 circuitized card through a first and second set of connections, the first set of
8 connections being interposed between the bottom surface of the first circuitized
9 card and the top surface of the interposer, the second set of connections being
10 interposed between the bottom surface of the interposer and the top surface of
11 the second circuitized card, wherein (a) the bottom surface of the second
12 circuitized card has a third set of connections for attaching the second circuitized
13 card to a system card, (b) the opening in the interposer, the bottom surface of
14 the first circuitized card, and the top surface of the second circuitized card form a
15 cavity for containing at least one electronic component, and (c) the interposer,
16 first circuitized card, and second circuitized card are circuitized multi-layer
17 organic laminate cards.

Remarks

The above amendment is submitted in response to the final office action dated March 13, 2002. The amendments to claim 1 and 20 incorporate the limitations of claim 11 and 34 respectively. Applicants have canceled all the claims other than those dependent from claims 1 and 20. In as much as the office action indicated claims 11 and 34 as allowable if rewritten in independent form, applicants submit that the remaining claims are now patentable over the prior art of record.

For the above reasons, applicants submit that the application is now in condition for allowance. Such allowance is earnestly and respectfully solicited.

Respectfully submitted,
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Amendments to the Claims

1 1. (thrice amended) A package for containing electronic components, the
2 package comprising:
3 a first circuitized card;
4 a second circuitized card;
5 an interposer interposed between the first and second circuitized cards,
6 the interposer having an opening, the opening in the interposer and the first and
7 second circuitized card forming a cavity for containing at least one electronic
8 component
9 wherein the first circuitized card has a bottom surface and there is at least one
10 component mounted to the bottom surface, and wherein the interposer, first
11 circuitized card, and second circuitized card are circuitized multi-layer organic
12 laminate cards.

Cancel claims 11, 34 and 36-53.

1 20. (thrice amended) A package for containing electronic components, the
2 package comprising:
3 a first circuitized card having a top and bottom surface;
4 a second circuitized card having a top and bottom surface;
5 an interposer having an opening, a top surface, and a bottom surface, the
6 interposer being electrically connected to the first circuitized card and the second
7 circuitized card through a first and second set of connections, the first set of
8 connections being interposed between the bottom surface of the first circuitized
9 card and the top surface of the interposer, the second set of connections being
10 interposed between the bottom surface of the interposer and the top surface of
11 the second circuitized card, wherein (a) the bottom surface of the second
12 circuitized card has a third set of connections for attaching the second circuitized
13 card to a system card, [and wherein] (b) the opening in the interposer, the

14 bottom surface of the first circuitized card, and the top surface of the second
15 circuitized card [forms] form a cavity for containing at least one electronic
16 component, and (c) the interposer, first circuitized card, and second circuitized
17 card are circuitized multi-layer organic laminate cards.
